



SEMITRANS® 2N

Ultra Fast IGBT Module

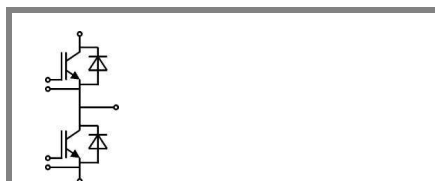
SKM 100GB125DN

Features

- N channel, homogeneous Si
- Low inductance case
- Short tail current with low temperature dependence
- High short circuit capability, self limiting to $6 \times I_{Cnom}$
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding Technology
- Large clearance (10 mm) and creepage distances (20 mm)

Typical Applications*

- Switched mode power supplies at $f_{sw} > 20$ kHz
- Resonant inverters up to 100 kHz
- Inductive heating
- Electronic welders at $f_{sw} > 20$ kHz



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Absolute Maximum Ratings			T _c = 25 °C, unless otherwise specified	
Symbol	Conditions		Values	Units
IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	T _j = 150 °C	T _{case} = 25 °C	100	A
		T _{case} = 85 °C	80	A
I _{CRM}	I _{CRM} =2xI _{Cnom}		150	A
V _{GES}			± 20	V
t _{psc}	V _{CC} = 600 V; V _{GE} ≤ 20 V; T _j = 125 °C V _{CES} < 1200 V		10	µs
Inverse Diode				
I _F	T _j = 150 °C	T _{case} = 25 °C	95	A
		T _{case} = 80 °C	65	A
I _{FRM}	I _{FRM} =2xI _{Fnom}		150	A
I _{FSM}	t _p = 10 ms; sin.	T _j = 150 °C	720	A
Module				
I _{t(RMS)}			200	A
T _{vj}			- 40 ... + 150	°C
T _{stg}			125	°C
V _{isol}	AC, 1 min.		4000	V

Characteristics			T _c = 25 °C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 2 mA		4,5	5,5	6,5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	T _j = 25 °C T _j = 125 °C		0,15	0,45	mA mA
V _{CE0}		T _j = 25 °C T _j = 125 °C				V V
r _{CE}	V _{GE} = 15 V	T _j = 25°C T _j = 125°C				mΩ mΩ
V _{CE(sat)}	I _{Cnom} = 75 A, V _{GE} = 15 V	T _j = °C _{chiplev.}		3,3	3,85	V
C _{ies}	V _{CE} = 25, V _{GE} = 0 V f = 1 MHz			5	6,6	nF
C _{oes}				0,72	0,9	nF
C _{res}				0,38	0,5	nF
Q _G	V _{GE} = 0 - +20V			650		nC
R _{Gint}	T _j = °C			5		Ω
t _{d(on)}	R _{Gon} = 8 Ω	V _{CC} = 600V I _C = 75A		80		ns
t _r				40		ns
E _{on}	R _{Goff} = 8 Ω	T _j = 125 °C V _{GE} = ± 15V		9		mJ
t _{d(off)}				360		ns
t _f				20		ns
E _{off}				3,5		mJ
R _{th(j-c)}	per IGBT				0,18	K/W



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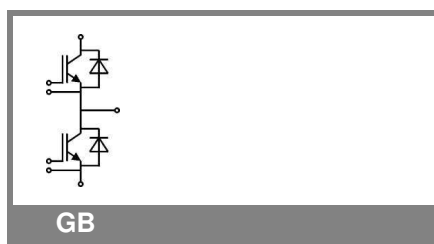
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Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 75$ A; $V_{GE} = 0$ V				
	$T_j = 25$ °C _{chiplev.}		2	2,5	V
	$T_j = 125$ °C _{chiplev.}		1,8		V
V_{F0}	$T_j = 25$ °C		1,1	1,2	V
	$T_j = 125$ °C				V
r_F	$T_j = 25$ °C		12	17,3	mΩ
	$T_j = 125$ °C				mΩ
I_{RRM}	$I_F = 75$ A		50		A
Q_{rr}	$di/dt = 800$ A/μs		11,5		μC
E_{rr}	$V_{GE} = 0$ V; $V_{CC} = 600$ V		4		mJ
$R_{th(j-c)D}$	per diode			0,5	K/W
Module					
L_{CE}			20	25	nH
$R_{CC'+EE'}$	res., terminal-chip	$T_{case} = 25$ °C	0,75		mΩ
		$T_{case} = 125$ °C	1		mΩ
$R_{th(c-s)}$	per module			0,05	K/W
M_s	to heat sink M6		3	5	Nm
M_t	to terminals M5		2,5	5	Nm
w				160	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.

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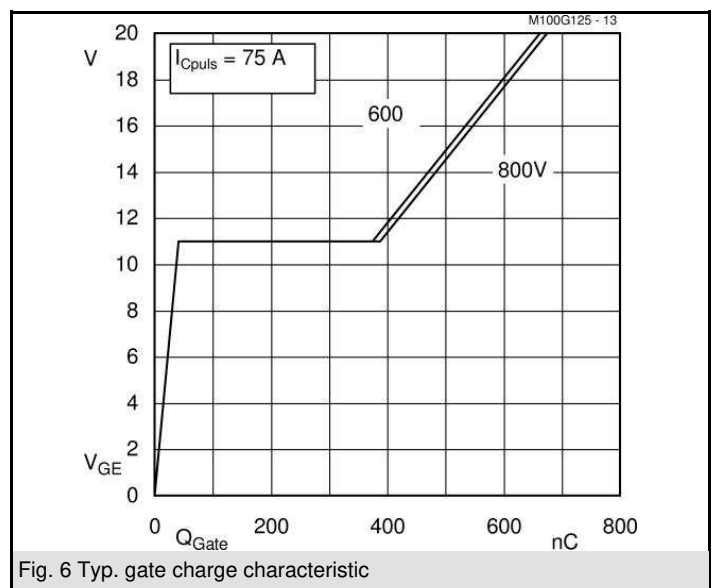
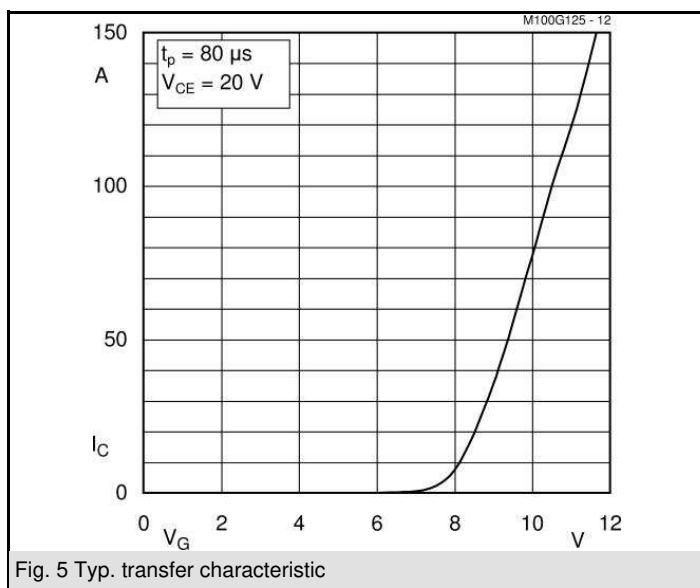
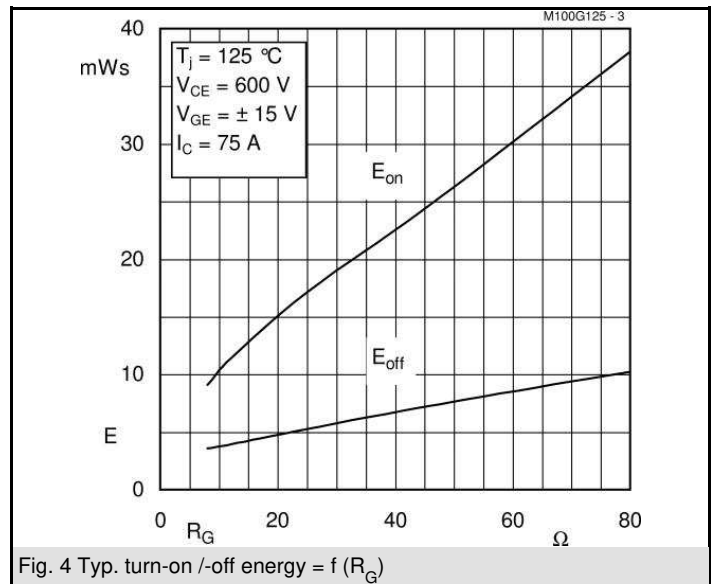
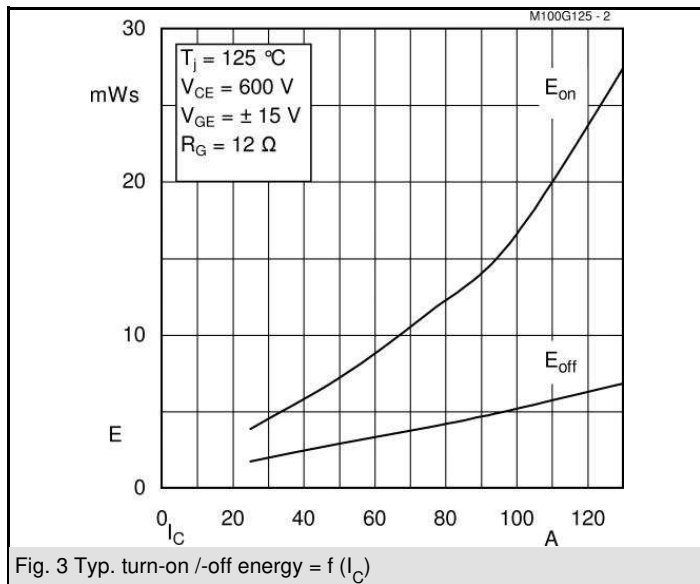
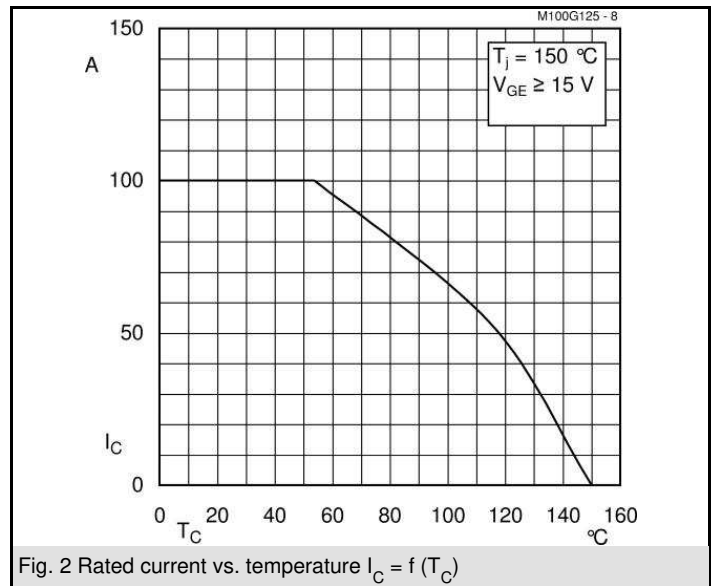
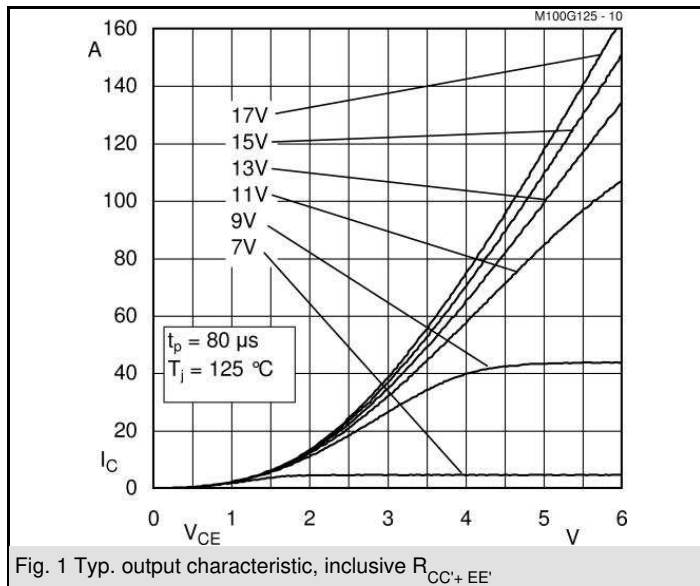
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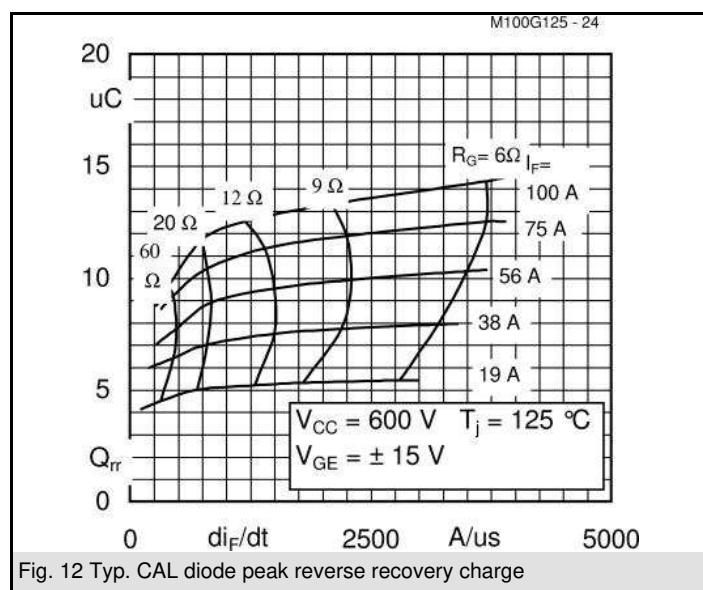
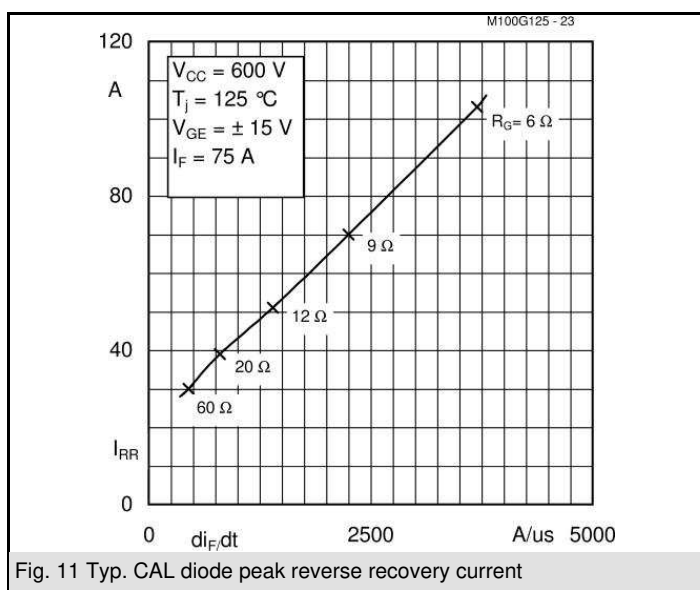
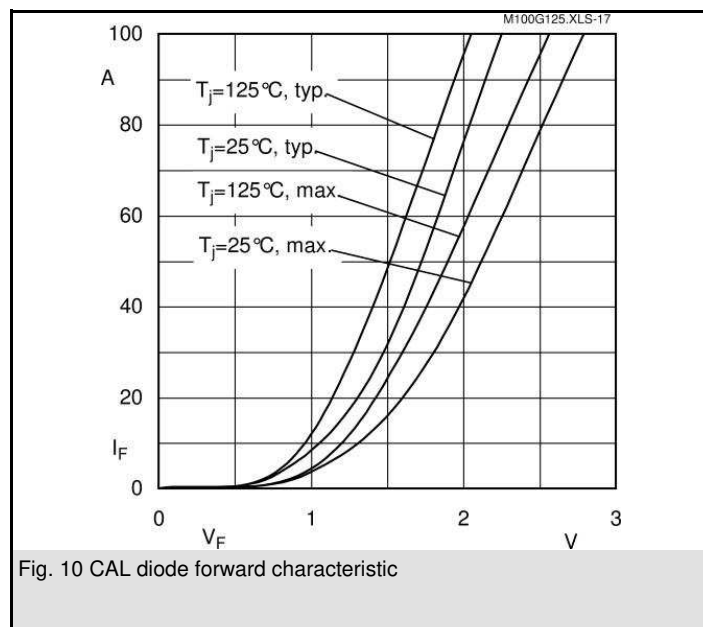
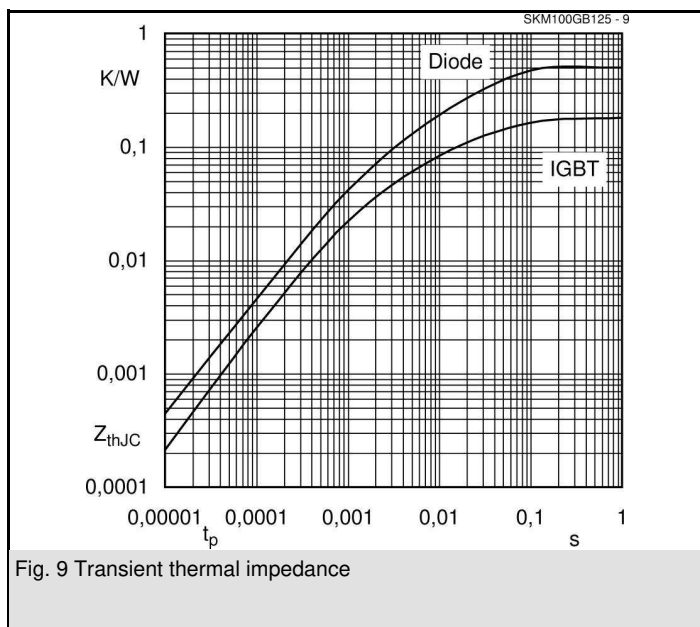
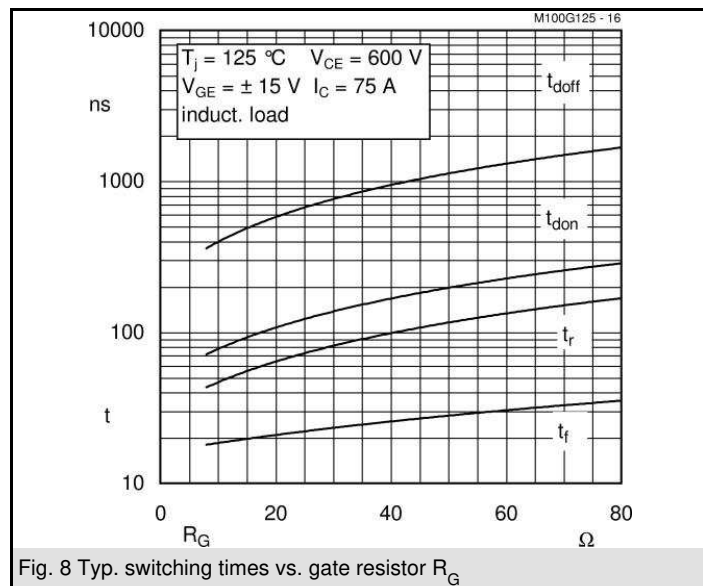
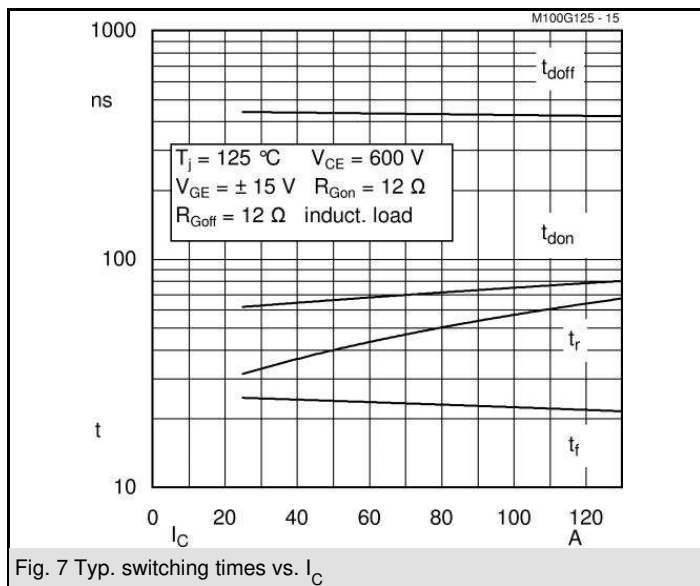
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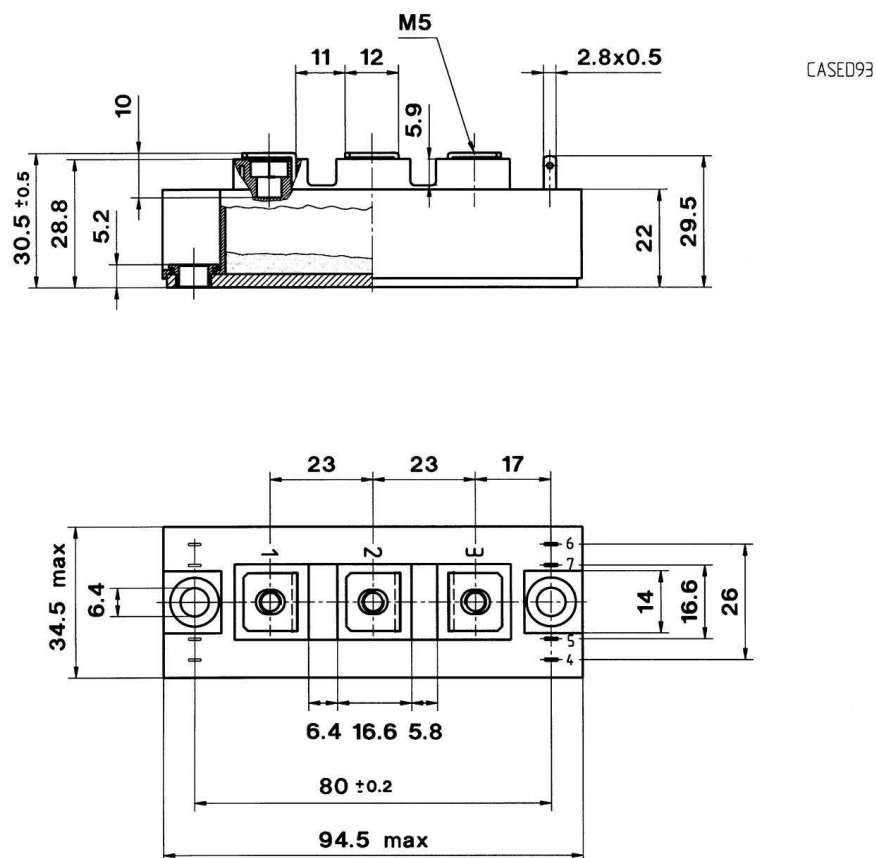
Z_{th}			
Symbol	Conditions	Values	Units
Z_{th(j-c)I}			
R _i	i = 1	95	mk/W
R _i	i = 2	65	mk/W
R _i	i = 3	17,5	mk/W
R _i	i = 4	2,5	mk/W
tau _i	i = 1	0,0327	s
tau _i	i = 2	0,008	s
tau _i	i = 3	0,0017	s
tau _i	i = 4	0,008	s
Z_{th(j-c)D}			
R _i	i = 1	300	mk/W
R _i	i = 2	160	mk/W
R _i	i = 3	36	mk/W
R _i	i = 4	4	mk/W
tau _i	i = 1	0,054	s
tau _i	i = 2	0,001	s
tau _i	i = 3	0,0015	s
tau _i	i = 4	0,1	s



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Case D 93

